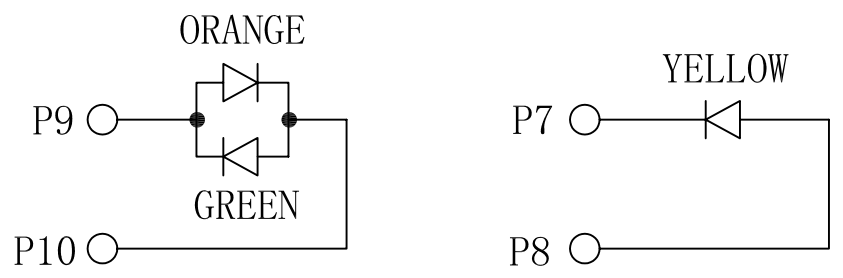
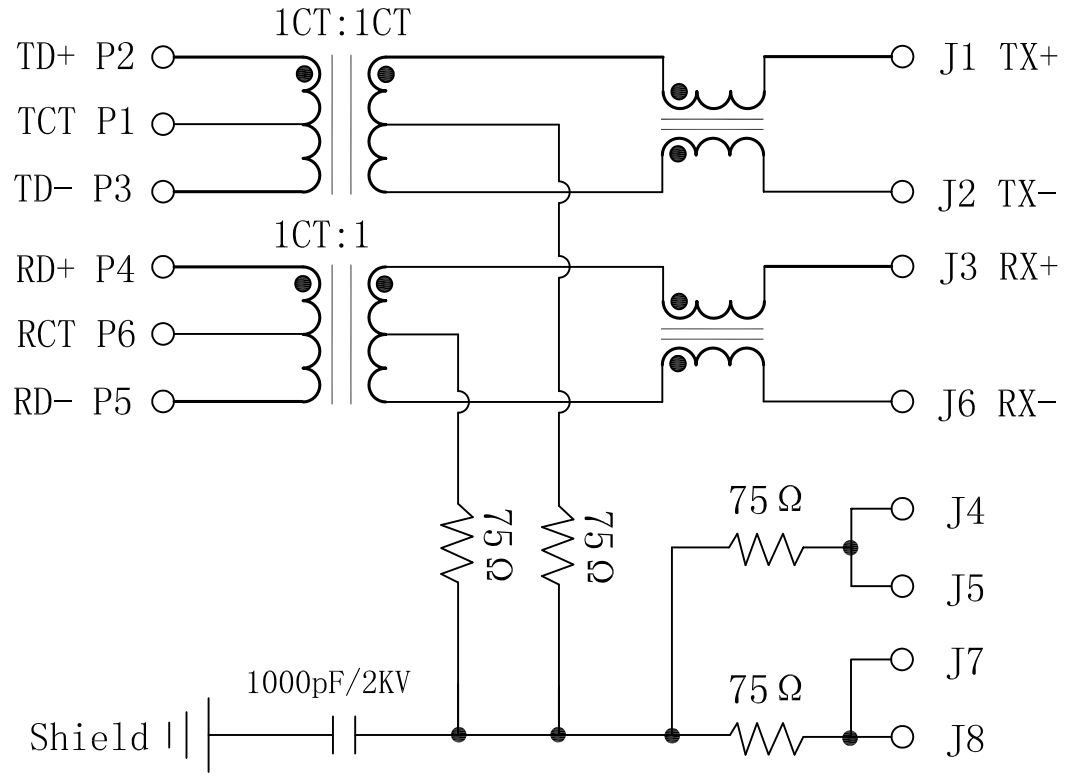


Schematic:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		18/11/2009	



Electrical Specification: @25°C

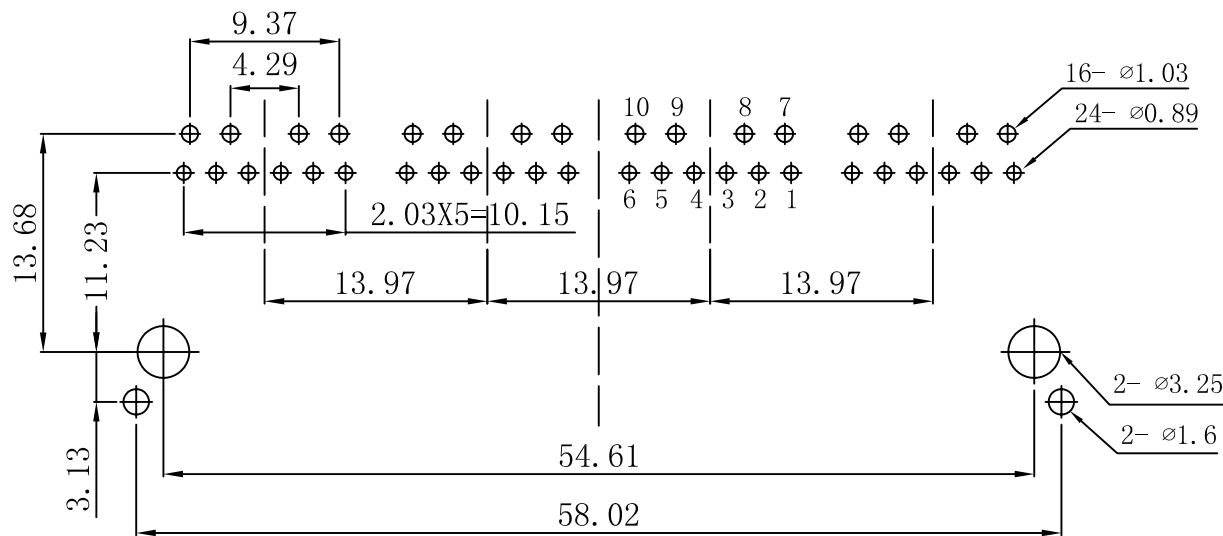
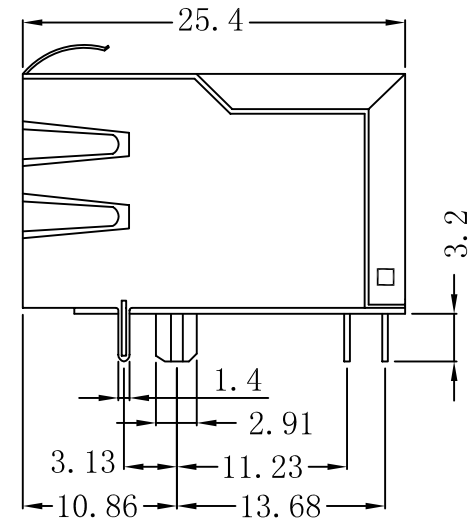
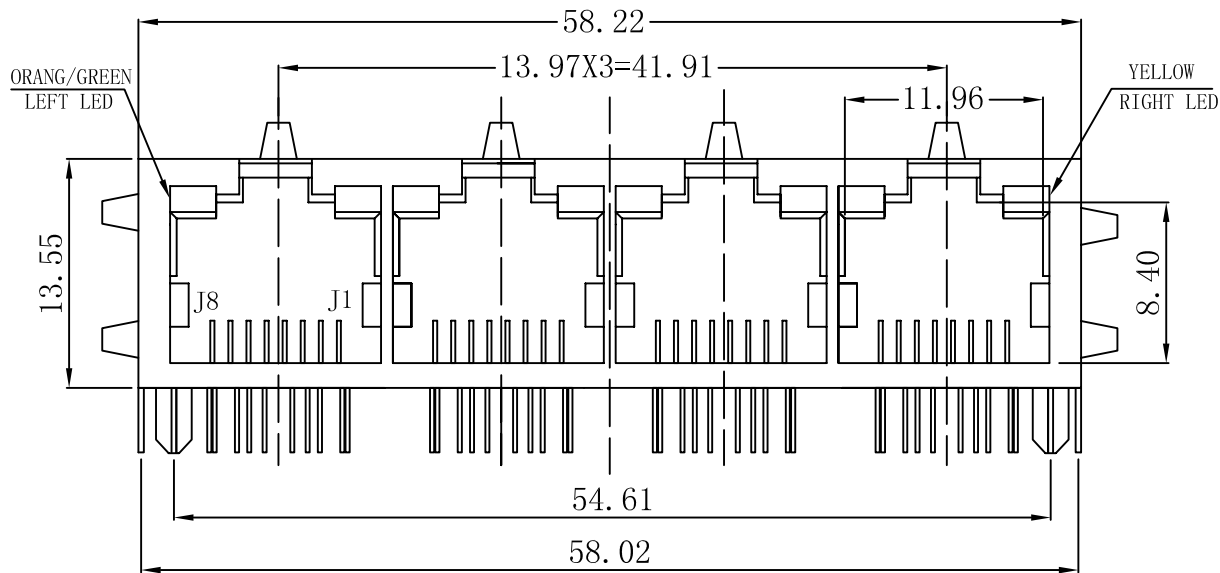
1. TURNS RATIO:
TX=1CT:1 RX=1CT:1
2. OCL:
350uH MIN @100KHz/100mVRMS, 8mA DC BIAS
3. INSERTION LOSS:
-1.0dB MAX @ 1MHz TO 100MHz
4. RETURN LOSS:
-18dB MIN @ 1MHz TO 30MHz
-18+20LOG (F/30MHz) dB MIN @ 30MHz TO 60MHz
-12dB MIN @ 60MHz TO 80MHz
5. CROSS TALK (TX - RX):
-70dB MIN @ 500KHz TO 1MHz
-50dB MIN @ 10MHz
-45dB MIN @ 30MHz
-40dB MIN @ 50MHz
-35dB MIN @ 100MHz
6. CM TO CM REJ (dB MIN):
-70 @100KHz TO 1MHz
-47 @10MHz; -42 @30MHz
-37 @60MHz; -30 @100MHz
7. CM TO DM REJ (dB MIN):
-70 @100KHz-1MHz
-60 @10MHz; -50 @30MHz
-45 @60MHz; -40 @100MHz
8. HiPot (Isolation Voltage): 1500Vrms.
9. OPERATING TEMPERATURE: -40°C ~ +85°C.



X:X	±0.20	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX	±0.10	CHKD:	TITLE: RJ45 1×4 Tab-Up Jack With 10/100 Base-TX Magnetic Modules	
X:XXX	±0.05	DR: TOM	PART NO.: LPJ42011KONL	
ANGLES	±1°	UNIT: mm		
	SCALE: 2/1	SHEET: 1/2	REV: A	DWG NO.: LP09111810

Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		18/11/2009	



SUGGESTED PCB LAYOUT (TOP VIEW)

NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-on-Motherboard (LOM), hub and Switches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
Housing: Thermoplastic UL94V-0
Contact/Shield: Copper alloy
Shield plating: Nickel
Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max
Wave solder tip temperature time: 5 Sec Max



X:X	±0.20	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX	±0.10	CHKD:	
X:XXX	±0.05	DR: TOM	TITLE: RJ45 1×4 Tab-Up Jack With 10/100 Base-TX Magnetic Modules
ANGLES	±1°	UNIT: mm	PART NO.: LPJ42011KONL
	SCALE: 2/1	SHEET: 2/2	REV: A
			DWG NO.: LP09111810